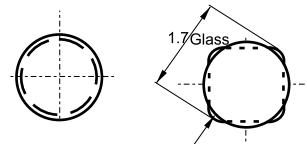
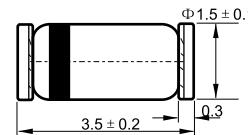




MINI MELF



Dimension in millimeters

Features

- ◊ High Voltage Switching Device
- ◊ Mini Melf package
- ◊ Surface device type mounting
- ◊ Hermetically sealed glass
- ◊ Compression bonded construction
- ◊ All external surface are corrosion resistant and leads are readily solderable
- ◊ RoHS compliant
- ◊ Matte Tin (Sn) lead finish
- ◊ Color band indicates Negative Polarity

Maximum Ratings and Electrical Characteristics

Rating at 25°C ambient temperature unless otherwise specified.

Single phase, half wave, 60 Hz, resistive or inductive load.

For capacitive load, derate current by 20%

Maximum Ratings

Type Number	Symbol	Value	Units
Repetitive Peak Reverse Voltage	V _{RRM}	250	V
Average Rectified Forward Current	I _{F(AV)}	200	mA
Non-Repetitive Peak Forward Surge Current Pulse Width = 1.0 Second Pulse Width = 1.0 usecond	I _{FSM}	1.0 4.0	A
Power Dissipation	P _d	500	mW
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to + 200	°C

Electrical Characteristics

Type Number	Symbol	Min	Max	Units
Breakdown Voltage BAV100 BAV101 BAV102 BAV103	B _V	60		V
		120		
		200		
		250		
Forward Voltage IF= 100mA	V _F		1.0	V
Peak Reverse Current BAV100 BAV101 BAV102 BAV103	IR		100	nA
			100	
			100	
			100	
Thermal Resistance, Junction to Ambient	R _{θJA}		350	°C/W
Junction Capacitance VR=0, f=1.0MHz	C _j	-	5.0	pF
Reverse Recovery Time (Note)	trr	-	50	nS

Notes: Reverse Recovery Test Conditions: IF=IR=30mA, Irr=3mA, RL=100Ω.



RATINGS AND CHARACTERISTIC CURVES (BAV100/101/102/103)

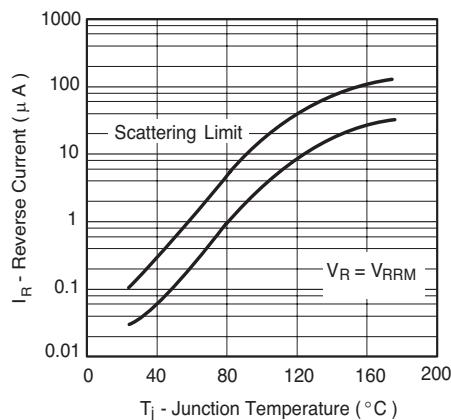


Fig. 1 Reverse Current vs. Junction Temperature

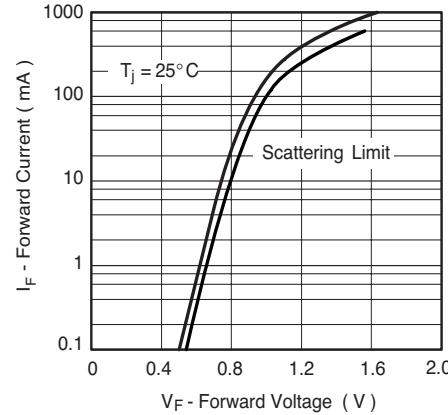


Fig. 2 Forward Current vs. Forward Voltage

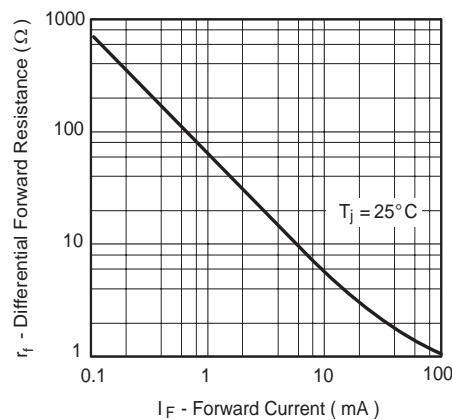


Fig. 3 Differential Forward Resistance vs. Forward Current